

IRF7469TRPBF-VB Datasheet N-Channel 40-V (D-S) MOSFET

PRODUCT SUMMARY						
V _{DS} (V)	$R_{DS(on)}\left(\Omega\right)$	I _D (A) ^d	Q _g (Typ.)			
40	0.014 at V _{GS} = 10 V	10	15 nC			
	0.016 at V _{GS} = 4.5 V	9	13110			

SO-8 S 1 8 D S 2 7 D S 3 6 D G 4 5 D

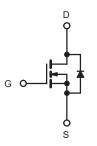
FEATURES

- Halogen-free According to IEC 61249-2-21 Definition
- Trench Power MOSFET
- 100 % R_g Tested
- 100 % UIS Tested
- Compliant to RoHS directive 2002/95/EC



APPLICATIONS

- · Synchronous Rectification
- POL, IBC
 - Secondary Side



N-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS T _A = 25 °C, unless otherwise noted					
Parameter	Symbol	Limit	Unit		
Drain-Source Voltage	V_{DS}	40	V		
Gate-Source Voltage	V_{GS}	± 20	v		
	T _C = 25 °C		10		
Continuous Drain Current (T _{.I} = 150 °C)	T _C = 70 °C	Ī	8		
Continuous Diain Current (1) = 130 C)	T _A = 25 °C	- I _D	10.4 ^{a, b}	Α	
	T _A = 70 °C		8.8 ^{a, b}	^	
Pulsed Drain Current		I _{DM}	50		
Avalanche Current Avalanche Energy L = 0.1 mH		I _{AS}	15		
		E _{AS}	11	mJ	
Continuous Source-Drain Diode Current	T _C = 25 °C	- I _S	5	A	
Continuous Source-Diam Diode Current	T _A = 25 °C		2.1 ^{a, b}	^	
	T _C = 25 °C		6		
Maximum Power Dissipation	T _C = 70 °C	P _D	3.8	w	
Maximum Fower Dissipation	T _A = 25 °C		2.5 ^{a, b}	VV	
	T _A = 70 °C	1	1.6 ^{a, b}		
Operating Junction and Storage Temperature	T _J , T _{stg}	- 55 to 150	°C		

THERMAL RESISTANCE RATINGS						
Parameter	Symbol	Typical	Maximum	Unit		
Maximum Junction-to-Ambient ^{a, c}	t ≤ 10 s	R_{thJA}	37	50	°C/W	
Maximum Junction-to-Foot (Drain)	Steady State	R_{thJF}	17	21	C/ VV	

Notes:

- a. Surface Mounted on 1" x 1" FR4 board.
- b. t = 10 s.
- c. Maximum under Steady State conditions is 85 °C/W.
- d. Based on T_C = 25 °C.



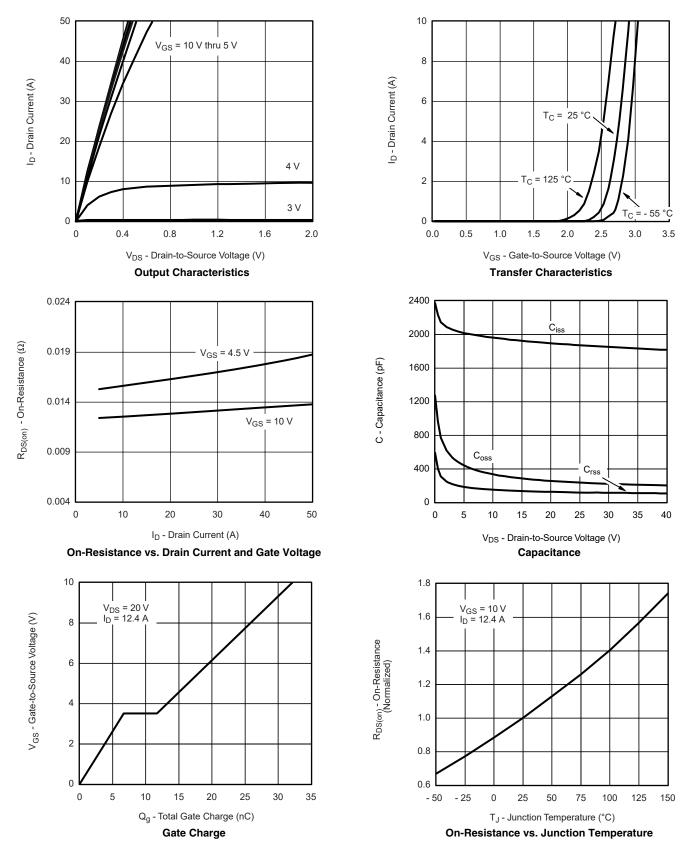
Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit
Static					l	
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0 \text{ V, I}_{D} = 250 \mu\text{A}$	40			V
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	I _D = 250 µA		40		mV/°C
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_J$			- 6		
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}$, $I_{D} = 250 \mu A$	1		3	V
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA
7 0 1 1/1 1 2 1 0 1		V _{DS} = 40 V, V _{GS} = 0 V			1	μA
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 40 V, V _{GS} = 0 V, T _J = 55 °C			5	
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \ge 5 \text{ V}, V_{GS} = 10 \text{ V}$	50			Α
		$V_{GS} = 10 \text{ V}, I_D = 12.4 \text{ A}$	0.014			1
Drain-Source On-State Resistance ^a	R _{DS(on)}	$V_{GS} = 4.5 \text{ V}, I_D = 10.8 \text{ A}$				Ω
Forward Transconductance ^a	g _{fs}	V _{DS} = 15 V, I _D = 12.4 A		56		S
Dynamic ^b					<u> </u>	l
Input Capacitance	C _{iss}			2000		
Output Capacitance	C _{oss}	$V_{DS} = 20 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		260		pF
Reverse Transfer Capacitance	C _{rss}			150		
Total Gate Charge	0	V _{DS} = 10 V, V _{GS} = 10 V, I _D = 12.4 A		33	50	
	Q _g		15	23	1	
Gate-Source Charge	Q_{gs}	V_{DS} = 10 V, V_{GS} = 4.5 V, I_{D} = 12.4 A		6.7		nC
Gate-Drain Charge	Q_{gd}			5.1		1
Gate Resistance	R_g	f = 1 MHz		1.4	2.1	Ω
Turn-On Delay Time	t _{d(on)}			25	40	
Rise Time	t _r	V_{DD} = 20 V, R_L = 2 Ω		12	20	1
Turn-Off Delay Time	t _{d(off)}	$I_D\cong$ 10 A, V_{GEN} = 4.5 V, R_g = 1 Ω		25	40	
Fall Time	t _f			10	15	
Turn-On Delay Time	t _{d(on)}			10	15	ns
Rise Time	t _r	V_{DD} = 20 V, R_L = 2 Ω		15	25	
Turn-Off Delay Time	t _{d(off)}	$I_D\cong$ 10 A, V_{GEN} = 10 V, R_g = 1 Ω		30	45	
Fall Time	t _f			10	15	
Drain-Source Body Diode Characteristi	cs					1
Continuous Source-Drain Diode Current	I _S	T _C = 25 °C			30	٨
Pulse Diode Forward Current	I _{SM}				50	Α
Body Diode Voltage	V_{SD}	I _S = 10 A, V _{GS} = 0 V		0.8	1.2	V
Body Diode Reverse Recovery Time	t _{rr}			30	60	ns
Body Diode Reverse Recovery Charge Q _{rr}		L = 10 A dl/dt = 100 A/··· T = 25 °C		26	52	nC
Reverse Recovery Fall Time	t _a	$I_F = 10 \text{ A}, \text{ dI/dt} = 100 \text{ A/}\mu\text{s}, T_J = 25 °\text{C}$		17.5		1
Reverse Recovery Rise Time	t _b			12.5		ns

Notes:

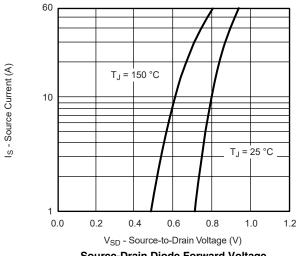
- a. Pulse test; pulse width $\leq 300~\mu s,~duty~cycle \leq 2~\%$
- b. Guaranteed by design, not subject to production testing.

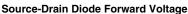
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

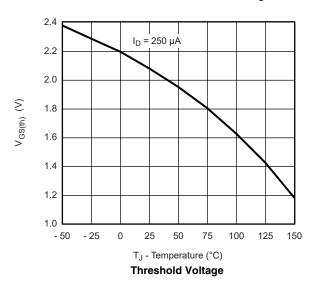






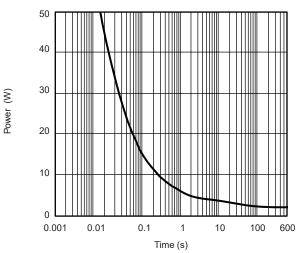




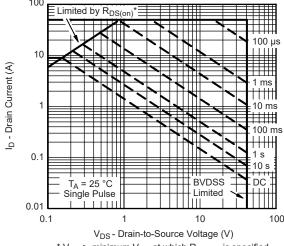


0.030 I_D = 12.4 A 0.025 $\mathsf{R}_{\mathsf{DS}(\mathsf{on})}$ - On-Resistance (Ω) 0.020 125 °C 0.015 0.010 25 °C 0.005 0.000 0 10 V_{GS} - Gate-to-Source Voltage (V)

On-Resistance vs. Gate-to-Source Voltage



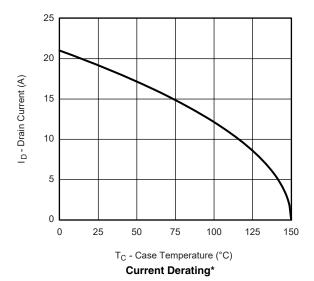
Single Pulse Power (Junction-to-Ambient)

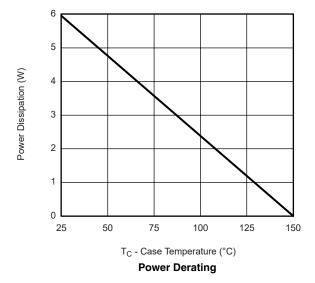


* V_{GS} > minimum V_{GS} at which $R_{DS(on)}$ is specified

Safe Operating Area, Junction-to-Ambient

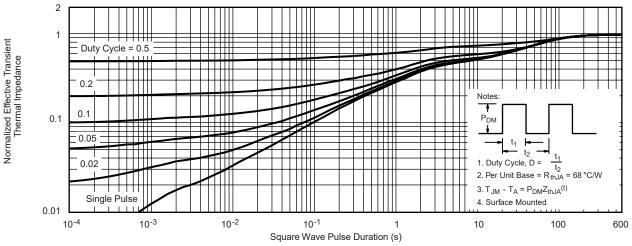




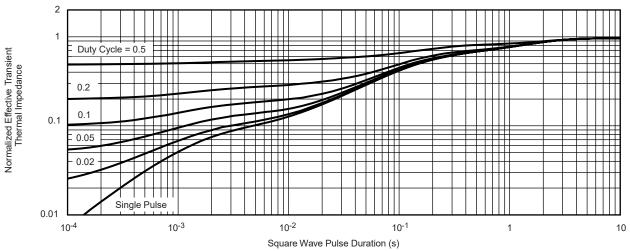


^{*} The power dissipation P_D is based on $T_{J(max)}$ = 150 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.





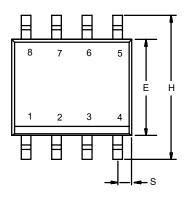
Normalized Thermal Transient Impedance, Junction-to-Ambient

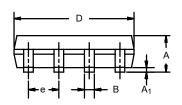


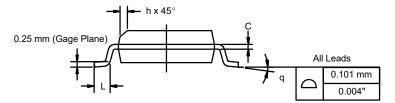
Normalized Thermal Transient Impedance, Junction-to-Foot



SOIC (NARROW): 8-LEAD JEDEC Part Number: MS-012





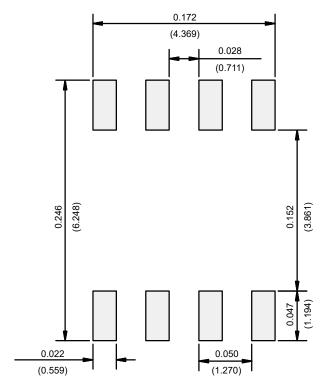


	MILLIN	IETERS	INC	HES		
DIM	Min	Max	Min	Max		
Α	1.35	1.75	0.053	0.069		
A ₁	0.10	0.20	0.004	0.008		
В	0.35	0.51	0.014	0.020		
С	0.19	0.25	0.0075	0.010		
D	4.80	5.00	0.189	0.196		
E	3.80	4.00	0.150	0.157		
е	1.27	BSC	0.050	0.050 BSC		
Н	5.80	6.20	0.228	0.244		
h	0.25	0.50	0.010	0.020		
L	0.50	0.93	0.020	0.037		
q	0°	8°	0°	8°		
S	0.44	0.64	0.018	0.026		
ECN: C-06527-Rev. I. 11-Sep-06						

DWG: 5498



RECOMMENDED MINIMUM PADS FOR SO-8



Recommended Minimum Pads Dimensions in Inches/(mm)



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